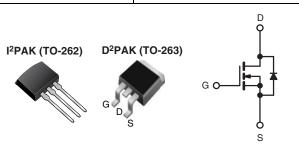




Power MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	900				
$R_{DS(on)}(\Omega)$	V _{GS} = 10 V 8.0				
Q _g (Max.) (nC)	38				
Q _{gs} (nC)	4.7				
Q _{gd} (nC)	21				
Configuration	Single				



FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- Pb RoHS'

HALOGEN

FREE

- Surface Mount (IRFBF20S, SiHFBF20S)
- Low-Profile Through-Hole (IRFBF20L, SiHFBF20L) COMPLIANT
- Available in Tape and Reel (IRFBF20S, SiHFBF20S)
- Dynamic dV/dt Rating
- 150 °C Operating Temperature
- Fast Switching
- Fully Avalanche Rated
- Compliant to RoHS Directive 2002/95/EC

DESCRIPTION

Third generation Power MOSFETs form Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The D²PAK is a surface mount power package capabel of the accommodating die sizes up to HEX-4. It provides the highest power capability and the lowest possible on-resistance in any existing surface mount package. The D²PAK is suitable for high current applications because of its low internal connection resistance and can dissipate up to 2.0 W in a typical surface mount application. The through-hole version (IRFBF20L, SiHFBF20L) is available for low-profile applications.

ORDERING INFORMATION							
Package	D ² PAK (TO-263)	D ² PAK (TO-263)	D ² PAK (TO-263)	I ² PAK (TO-262)			
Lead (Pb)-free and Halogen-free	SiHFBF20S-GE3	SiHFBF20STRL-GE3a	SiHFBF20STRR-GE3a	SiHFBF20L-GE3			
Lead (Pb)-free	IRFBF20SPbF	IRFBF20STRLPbFa	IRFBF20STRRPbFa	IRFBF20LPbF			
Lead (FD)-life	SiHFBF20S-E3	SiHFBF20STL-E3a	SiHFBF20STR-E3a	SiHFBF20L-E3			

N-Channel MOSFET

Note

a. See device orientation.

ABSOLUTE MAXIMUM RATINGS (T_C	= 25 °C, un	less otherwis	se noted)			
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage ^e			V _{DS}	900	V	
Gate-Source Voltage ^e			V _{GS}	± 20	\ \ \	
Continuous Drain Current	V _{GS} at 10 V	T _C = 25 °C T _C = 100 °C	- I _D	1.7		
Continuous Drain Current	VGS at 10 V	T _C = 100 °C		1.1	Α	
Pulsed Drain Current ^{a,e}			I _{DM}	6.8		
Linear Derating Factor				0.43	W/°C	
Single Pulse Avalanche Energy ^{b, e}			E _{AS}	180	mJ	
Repetitive Avalanche Current ^a			I _{AR}	1.7	Α	
Repetitive Avalanche Energy ^a			E _{AR}	5.4	mJ	
Maximum Dawar Dissination	T _C =	25 °C	Р	54	w	
Maximum Power Dissipation	T _A =	25 °C 25 °C	P_{D}	3.1	T VV	
Peak Diode Recovery dV/dt ^{c, e}			dV/dt	1.5	V/ns	
Operating Junction and Storage Temperature Range			T _J , T _{stg}	- 55 to + 150	°C	
Soldering Recommendations (Peak Temperature) for 10 s		<u> </u>	300 ^d	1		
Mounting Torque 6-32 or M3 screw				10	N	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. V_{DD} = 50 V; starting T_J = 25 °C, L = 117 mH, R_g = 25 Ω , I_{AS} = 1.7 A (see fig. 12).
- c. $I_{SD} \le 1.7 \text{ A}$, $dI/dt \le 70 \text{ A/}\mu\text{s}$, $V_{DD} \le V_{DS}$, $T_{J} \le 150 \text{ °C}$.
- d. 1.6 mm from case.
- e. Uses IRFBF20, SiHFBF20 data and test conditions.

^{*} Pb containing terminations are not RoHS compliant, exemptions may apply

IRFBF20S, SiHFBF20S, IRFBF20L, SiHFBF20L

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THERMAL RESISTANCE RATINGS							
PARAMETER SYMBOL TYP. MAX. UNIT							
Maximum Junction-to-Ambient (PCB Mounted, steady-state) ^a	R _{thJA}	-	40	°C/W			
Maximum Junction-to-Case	R_{thJC}	-	2.3				

Note

a. When mounted on 1" square PCB (FR-4 or G-10 material).

SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)									
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT		
Static									
Drain-Source Breakdown Voltage	V _{DS}	V _{GS}	= 0, I _D = 250 μA	900	-	-	V		
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C, I _D = 1 mA	-	1.1	-	mV/°C		
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2.0	-	4.0	V		
Gate-Source Leakage	I _{GSS}		V _{GS} = ± 20 V	-	-	± 100	nA		
Zero Gate Voltage Drain Current	1	V _{DS} =	= 900 V, V _{GS} = 0 V	-	-	100			
zero Gate voltage Drain Current	I _{DSS}	V _{DS} = 720 V	/, V _{GS} = 0 V, T _J = 125 °C	-	-	500	μA		
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	V _{GS} = 10 V I _D = 1.0 A ^b		-	8.0	Ω		
Forward Transconductance	9 _{fs}	V _{DS} = 50 V, I _D = 1.0 A ^b		0.6	-	-	S		
Dynamic									
Input Capacitance	C _{iss}		$V_{GS} = 0 V$	-	490	-	pF		
Output Capacitance	C _{oss}	1	$V_{DS} = 25 \text{ V},$	-	55	-			
Reverse Transfer Capacitance	C _{rss}	f = 1	.0 MHz, see fig. 5	-	18	-	1		
Total Gate Charge	Qg			-	-	38			
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V	$I_D = 1.7 \text{ A}, V_{DS} = 360 \text{ V},$ see fig. 6 and 13 ^b	-	-	4.7	nC		
Gate-Drain Charge	Q _{gd}	See lig. 0 and 13		-	-	21			
Turn-On Delay Time	t _{d(on)}	$V_{DD} = 450 \text{ V}, I_D = 1.7 \text{ A},$ $R_g = 18 \Omega, V_{GS} = 10 \text{ V}, \text{ see fig. } 10^b$		-	8.0	-			
Rise Time	t _r			-	21	-]		
Turn-Off Delay Time	t _{d(off)}			-	56	-	ns		
Fall Time	t _f			-	32	-			

SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT		
Drain-Source Body Diode Characteristics								
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the	-	-	1.7	Α		
Pulsed Diode Forward Current ^a	I _{SM}	integral reverse p - n junction diode	-	-	6.8	A		
Body Diode Voltage	V_{SD}	$T_J = 25 ^{\circ}\text{C}, \ I_S = 1.7 \text{A}, \ V_{GS} = 0 \text{V}^{\text{b}}$	-	-	1.5	V		
Body Diode Reverse Recovery Time	t _{rr}	$T_J = 25 ^{\circ}\text{C}, I_F = 1.7 \text{A}, \text{dI/dt} = 100 \text{A/}\mu\text{s}^b$	-	350	530	ns		
Body Diode Reverse Recovery Charge	Q _{rr}	$I_1 = 25$ C, $I_F = 1.7$ A, I_{A} and $I_{A} = 100$ A/ μ S	-	0.85	1.3	μC		
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L _S and L _D)				L _D)		

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width \leq 300 µs; duty cycle \leq 2 %.
- c. Uses IRFBF20/SiHFBF20 data and test conditions.

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

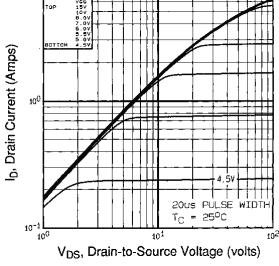
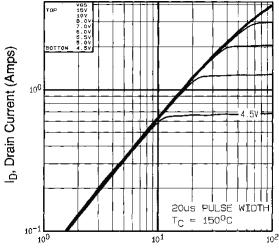


Fig. 1 - Typical Output Characteristics

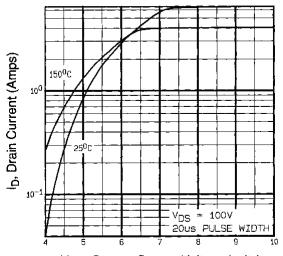


V_{DS}, Drain-to-Source Voltage (volts) Fig. 2 - Typical Output Characteristics

IRFBF20S, SiHFBF20S, IRFBF20L, SiHFBF20L

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V_{GS}, Gate-to-Source Voltage (volts) Fig. 3 - Typical Transfer Characteristics

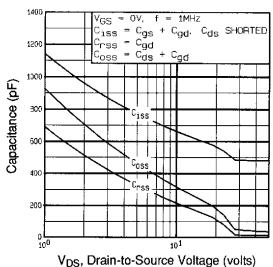


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

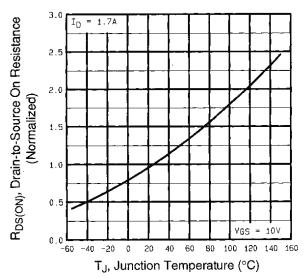


Fig. 4 - Normalized On-Resistance vs. Temperature

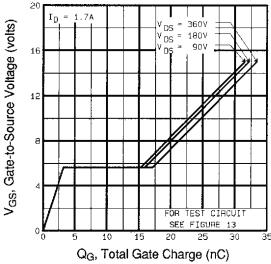


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

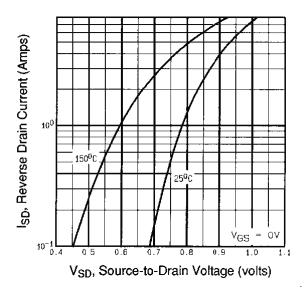


Fig. 7 - Typical Source-Drain Diode Forward Voltage

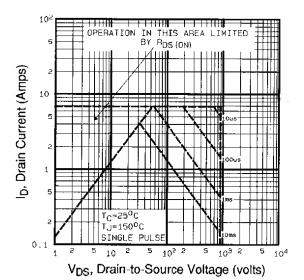


Fig. 8 - Maximum Safe Operating Area

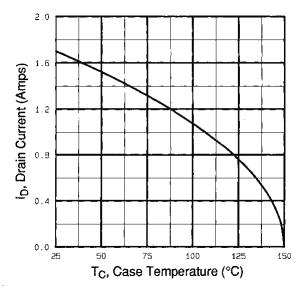


Fig. 9 - Maximum Drain Current vs. Case Temperature

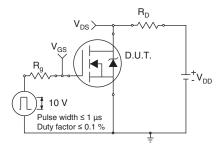


Fig. 10a - Switching Time Test Circuit

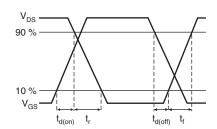


Fig. 10b - Switching Time Waveforms



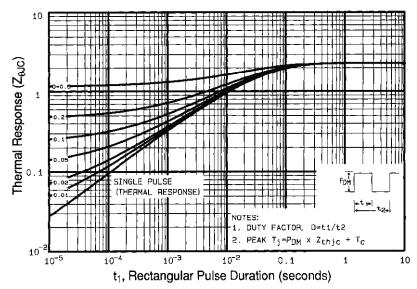


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

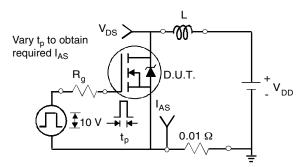


Fig. 12a - Unclamped Inductive Test Circuit

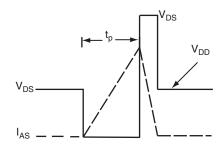


Fig. 12b - Unclamped Inductive Waveforms

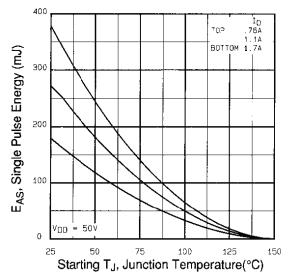


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

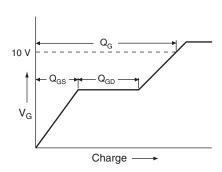


Fig. 13a - Basic Gate Charge Waveform

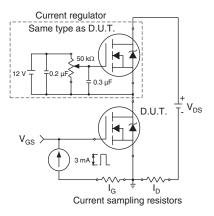


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit Circuit layout considerations D.U.T Low stray inductance Ground plane Low leakage inductance current transformer dV/dt controlled by R_g Driver same type as D.U.T. I_{SD} controlled by duty factor "D" D.U.T. - device under test

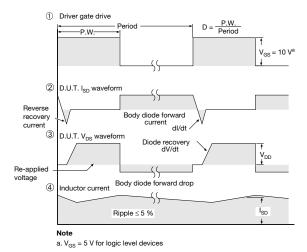


Fig. 14 - For N-Channel

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TO-263AB (HIGH VOLTAGE)







	MILLIN	METERS	INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.
Α	4.06	4.83	0.160	0.190
A1	0.00	0.25	0.000	0.010
b	0.51	0.99	0.020	0.039
b1	0.51	0.89	0.020	0.035
b2	1.14	1.78	0.045	0.070
b3	1.14	1.73	0.045	0.068
С	0.38	0.74	0.015	0.029
c1	0.38	0.58	0.015	0.023
c2	1.14	1.65	0.045	0.065
D	8.38	9.65	0.330	0.380

	MILLIMETERS		INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
D1	6.86	-	0.270	-	
Е	9.65	10.67	0.380	0.420	
E1	6.22	-	0.245	ı	
е	2.54	BSC	0.100 BSC		
Н	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	ı	0.066	
L2	-	1.78	-	0.070	
L3	0.25 BSC		0.010	BSC	
L4	4.78	5.28	0.188	0.208	

ECN: S-82110-Rev. A, 15-Sep-08

DWG: 5970

Notes

- 1. Dimensioning and tolerancing per ASME Y14.5M-1994.
- 2. Dimensions are shown in millimeters (inches).
- 3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body at datum A.
- 4. Thermal PAD contour optional within dimension E, L1, D1 and E1.
- 5. Dimension b1 and c1 apply to base metal only.
- 6. Datum A and B to be determined at datum plane H.
- 7. Outline conforms to JEDEC outline to TO-263AB.

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RECOMMENDED MINIMUM PADS FOR D²PAK: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)

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